



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUA190N08S5N028	Issued	22. May 2021
MA#	MA005423917		
Package	PG-HSOF-5-4	Weight*	369.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.072	0.83	0.83	8309	8309
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.10	13.11	130974	131144
wire	noble metal	gold	7440-57-5	0.052	0.01	0.01	139	139
encapsulation	inorganic material	zinc oxide	1314-13-2	1.405	0.38		3800	
	miscellaneous	miscellaneous	-	5.619	1.52		15201	
	plastics	epoxy resin	-	21.073	5.70		57005	
	inorganic material	silicon dioxide	60676-86-0	112.390	30.40	38.00	304024	380030
lead finish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9936	9936
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.056	0.02		152	
	noble metal	silver	7440-22-4	0.070	0.02		190	
	non noble metal	lead	7439-92-1	2.685	0.73	0.77	7262	7604
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		76	
	non noble metal	copper	7440-50-8	28.224	7.63	7.64	76348	76447
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		386	
	non noble metal	copper	7440-50-8	142.638	38.60	38.65	385848	386350
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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